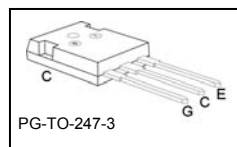
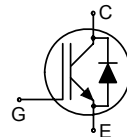


Reverse Conducting IGBT with monolithic body diode

Features:

- 1.5V typical saturation voltage of IGBT
- Trench and Fieldstop technology for 900 V applications offers :
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
 - easy parallel switching capability due to positive temperature coefficient in $V_{CE(sat)}$
- Low EMI
- Qualified according to JEDEC¹ for target applications
- Application specific optimisation of inverse diode
- Pb-free lead plating; RoHS compliant



Applications:

- Microwave Oven
- Soft Switching Applications for ZCS

Type	V_{CE}	I_C	$V_{CE(sat)}, T_j=25^\circ\text{C}$	$T_{j,max}$	Marking	Package
IHW30N90R	900V	30A	1.5V	175°C	H30R90	PG-TO-247-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	900	V
DC collector current	I_C	60 30	A
$T_C = 25^\circ\text{C}$			
$T_C = 100^\circ\text{C}$			
Pulsed collector current, t_p limited by $T_{j,max}$	I_{Cpuls}	90	
Turn off safe operating area $V_{CE} \leq 900\text{V}$, $T_j \leq 175^\circ\text{C}$	-	90	
Diode forward current	I_F	60 30	
$T_C = 25^\circ\text{C}$			
$T_C = 100^\circ\text{C}$			
Diode pulsed current, t_p limited by $T_{j,max}$	I_{Fpuls}	90	
Gate-emitter voltage	V_{GE}	± 20	V
Transient Gate-emitter voltage ($t_p < 5\text{ ms}$)		± 25	
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	454	W
Operating junction temperature	T_j	-40...+175	$^\circ\text{C}$
Storage temperature	T_{stg}	-55...+175	$^\circ\text{C}$
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

¹ J-STD-020 and JESD-022

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.33	K/W
Diode thermal resistance, junction – case	R_{thJCD}		0.33	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.5mA$	900	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=30A$ $T_j=25^{\circ}C$ $T_j=150^{\circ}C$ $T_j=175^{\circ}C$	- - -	1.5 1.6 1.7	1.7 - -	
Diode forward voltage	V_F	$V_{GE}=0V, I_F=30A$ $T_j=25^{\circ}C$ $T_j=150^{\circ}C$ $T_j=175^{\circ}C$	- - -	1.4 1.4 1.45	1.6 - -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=700\mu A, V_{CE}=V_{GE}$	5.1	5.8	6.4	
Zero gate voltage collector current	I_{CES}	$V_{CE}=900V, V_{GE}=0V$ $T_j=25^{\circ}C$ $T_j=150^{\circ}C$	- -	- -	5 2500	μA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	600	
						nA

Dynamic Characteristic

Input capacitance	C_{iss}	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	2889	-	pF
Output capacitance	C_{oss}		-	83	-	
Reverse transfer capacitance	C_{rss}		-	79	-	
Gate charge	Q_{Gate}	$V_{CC}=720V, I_C=30A$ $V_{GE}=15V$	-	200	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13	-	nH

Switching Characteristic, Inductive Load, at $T_j=25^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	Max.	
IGBT Characteristic						
Turn-off delay time	$t_{d(off)}$	$T_j=25^{\circ}C$ $V_{CC}=600V,$ $I_C=30A,$ $V_{GE}=0/15V,$ $R_G= 15\Omega$	-	511	-	mJ
Fall time	t_f		-	24	-	
Turn-on energy	E_{on}		-	-	-	
Turn-off energy	E_{off}		-	1.46	-	
Total switching energy	E_{ts}		-	1.46	-	

Switching Characteristic, Inductive Load, at $T_j=175^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
IGBT Characteristic						
Turn-off delay time	$t_{d(off)}$	$T_j=175^{\circ}C$ $V_{CC}=600V$, $I_C=30A$, $V_{GE}=0/15V$, $R_G=15\Omega$	-	594	-	mJ
Fall time	t_f		-	46	-	
Turn-on energy	E_{on}		-	-	-	
Turn-off energy	E_{off}		-	2.1	-	
Total switching energy	E_{ts}		-	2.1	-	

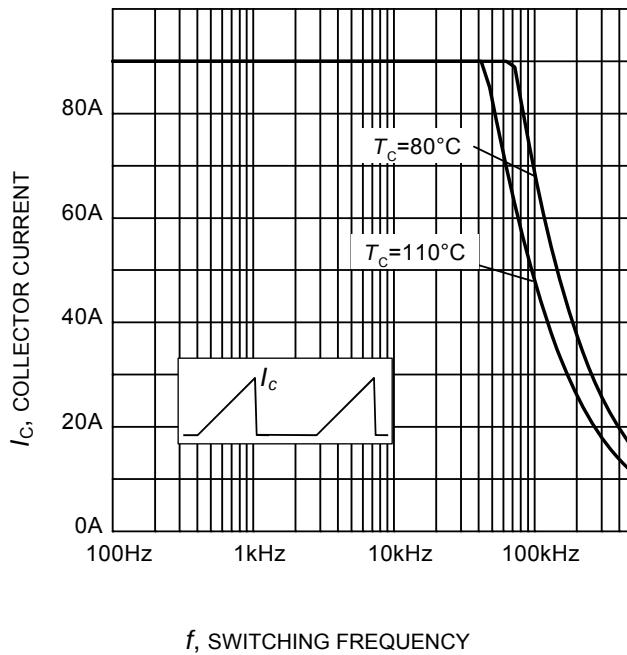


Figure 1. Collector current as a function of switching frequency for triangular current ($E_{on} = 0$, hard turn-off)
 $(T_j \leq 175^\circ\text{C}, D = 0.5, V_{CE} = 600\text{V}, V_{GE} = 0/+15\text{V}, R_G = 15\Omega)$

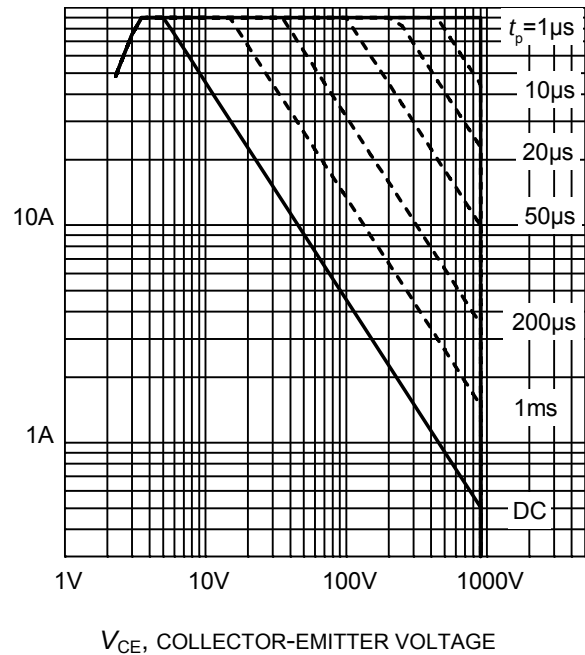


Figure 2. IGBT Safe operating area
 $(D = 0, T_C = 25^\circ\text{C}, T_j \leq 175^\circ\text{C}; V_{GE} = 15\text{V})$

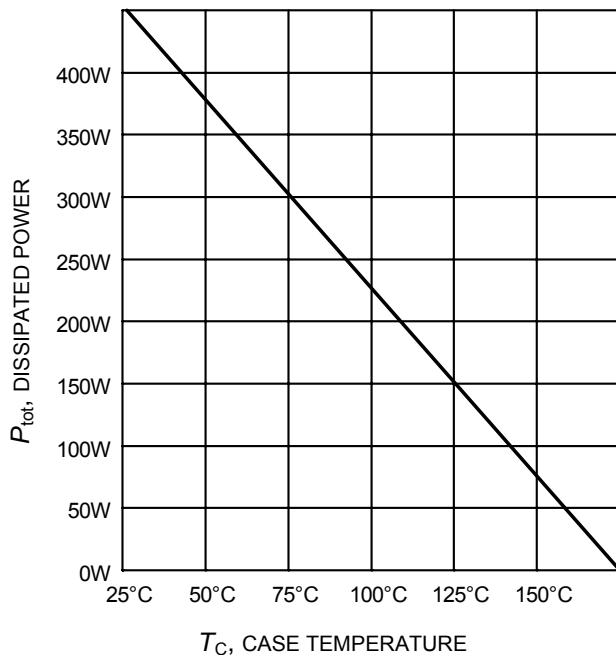


Figure 3. Power dissipation as a function of case temperature
 $(T_j \leq 175^\circ\text{C})$

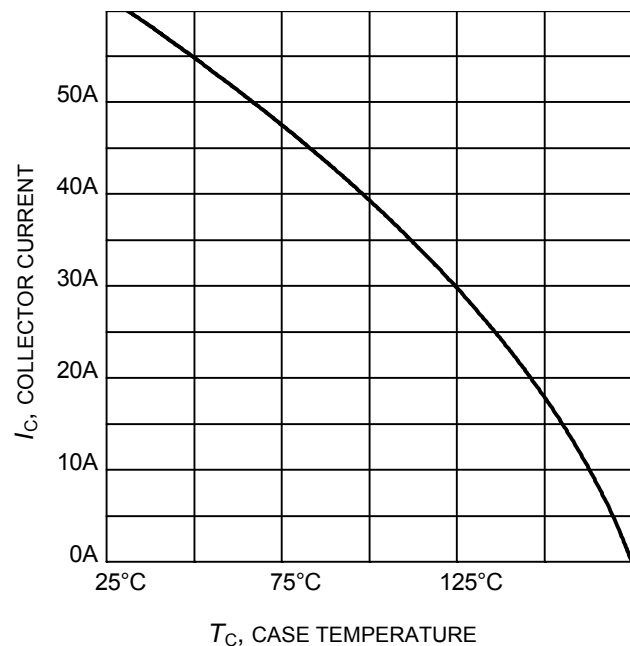


Figure 4. Collector current as a function of case temperature
 $(V_{GE} \geq 15\text{V}, T_j \leq 175^\circ\text{C})$

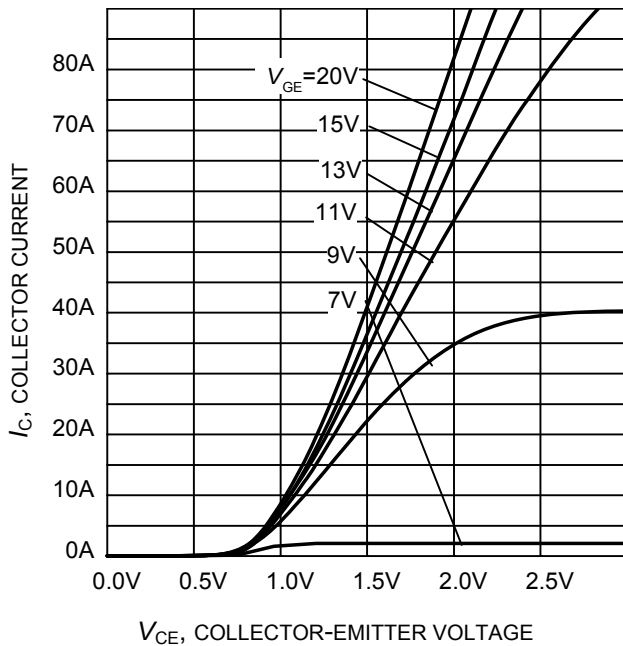


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

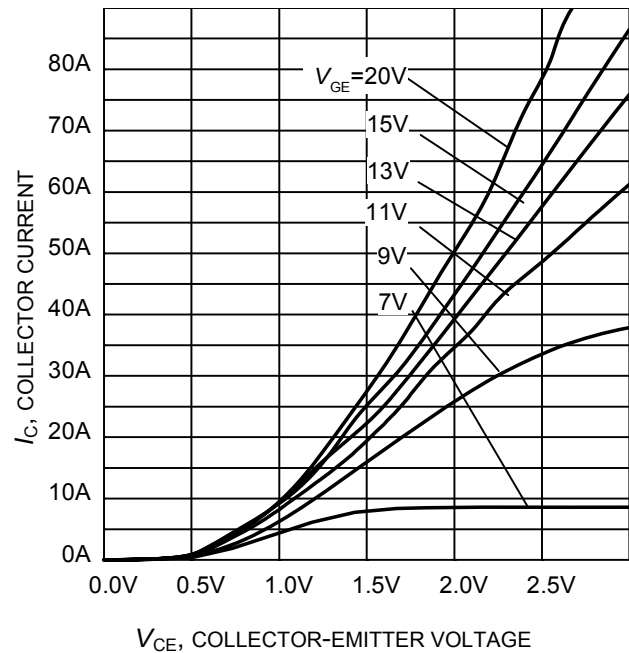


Figure 6. Typical output characteristic
($T_j = 175^\circ\text{C}$)

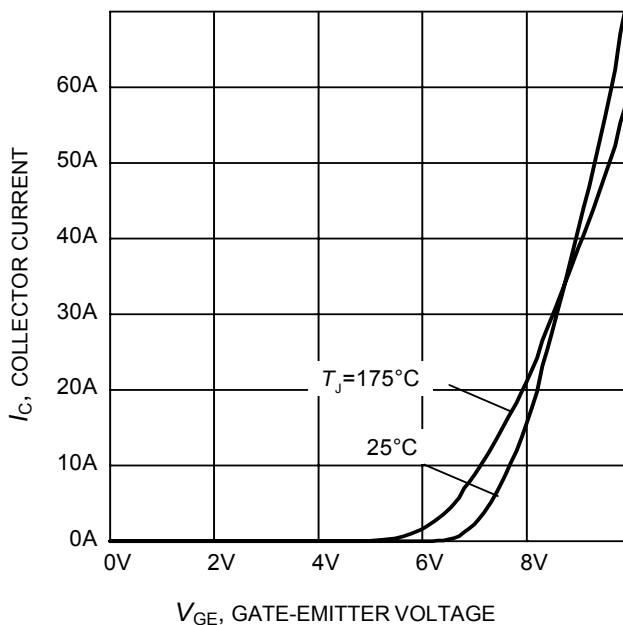


Figure 7. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

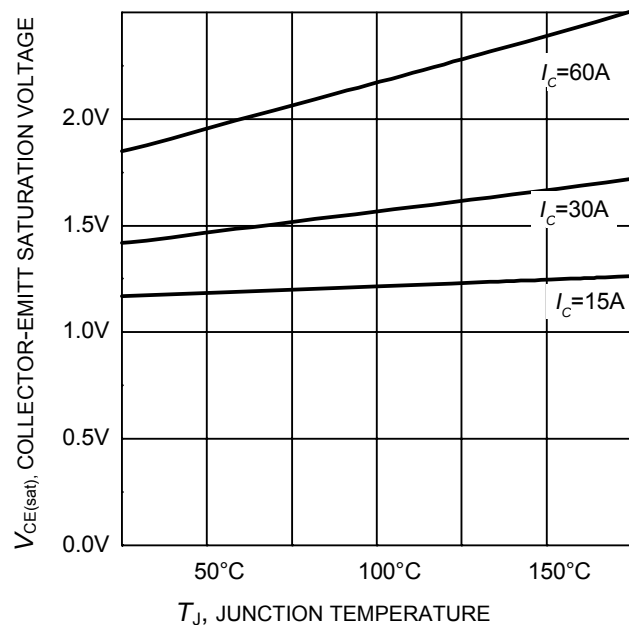


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

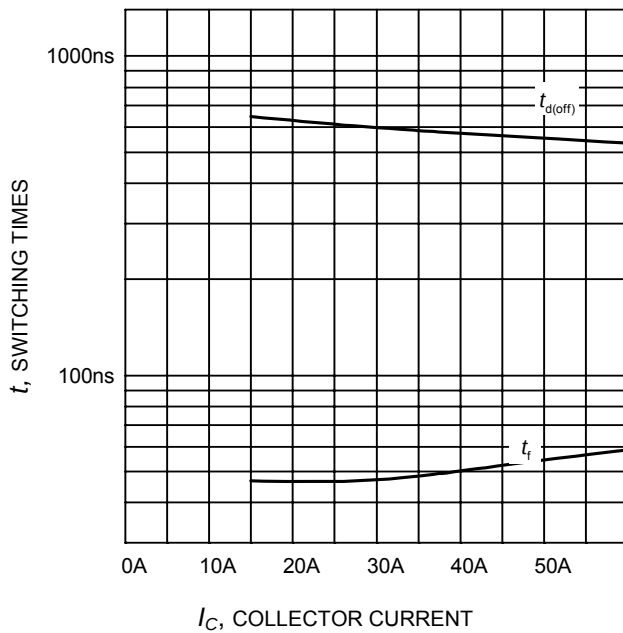


Figure 9. Typical switching times as a function of collector current
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=15\Omega$, Dynamic test circuit in Figure E)

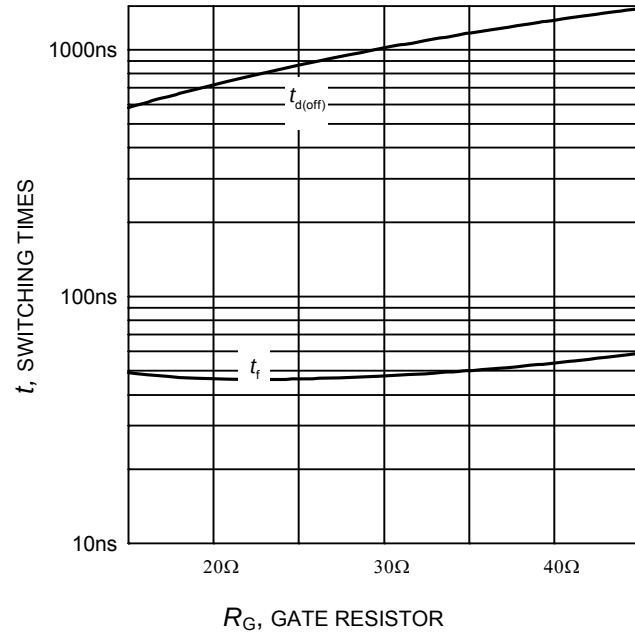


Figure 10. Typical switching times as a function of gate resistor
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=30\text{A}$, Dynamic test circuit in Figure E)

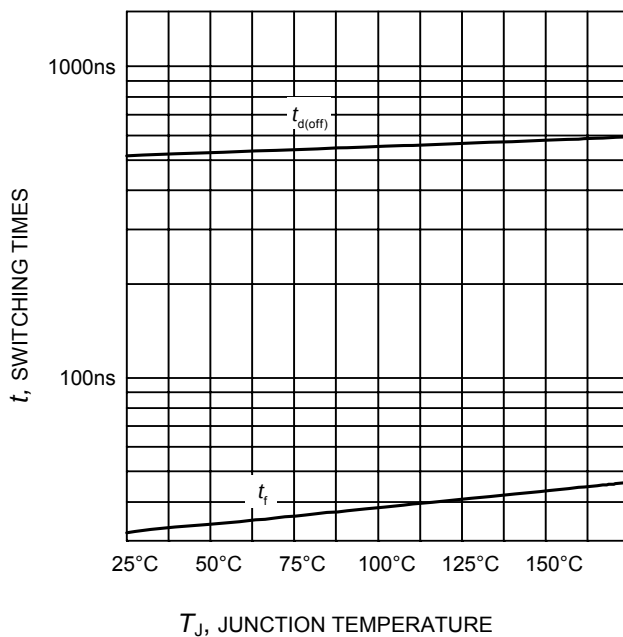


Figure 11. Typical switching times as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=30\text{A}$, $R_G=15\Omega$, Dynamic test circuit in Figure E)

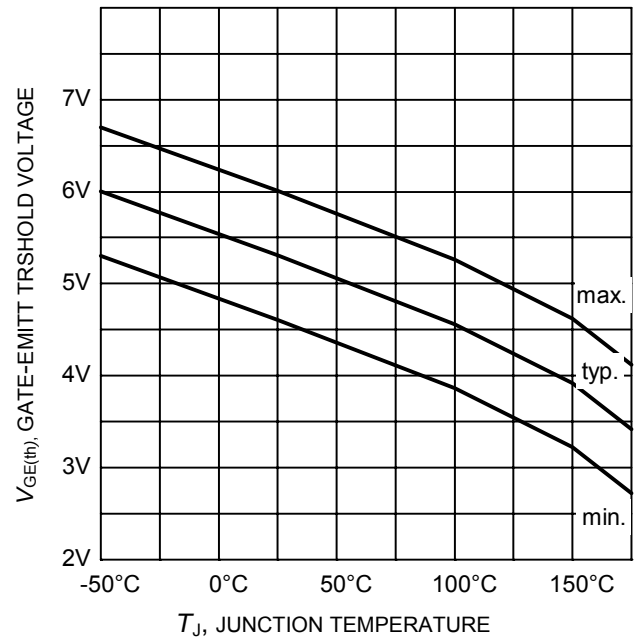


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
($I_C = 0.7\text{mA}$)

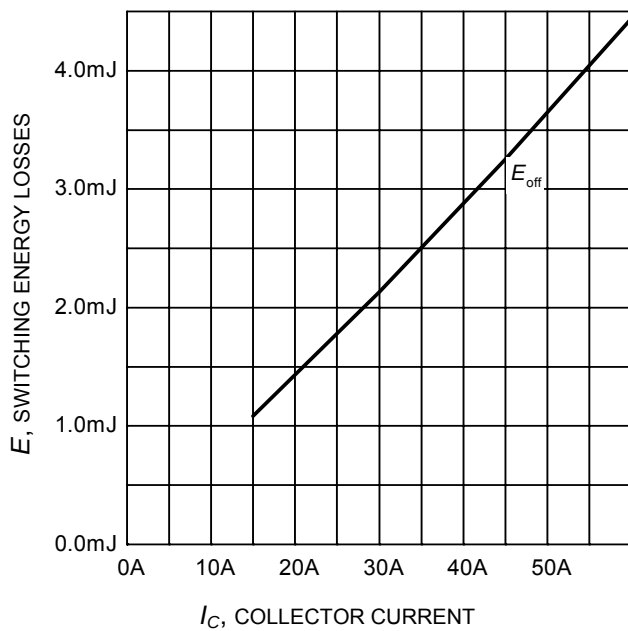


Figure 13. Typical switching energy losses as a function of collector current
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=15\Omega$, Dynamic test circuit in Figure E)

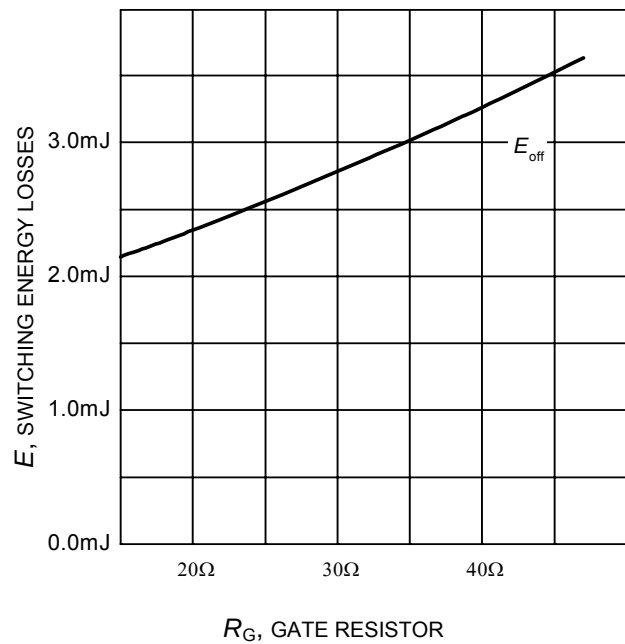


Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=30\text{A}$, Dynamic test circuit in Figure E)

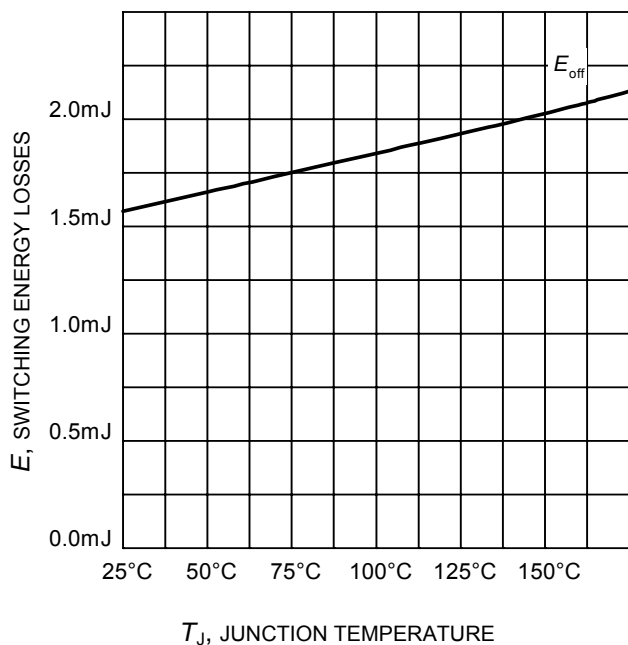


Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=30\text{A}$, $R_G=15\Omega$, Dynamic test circuit in Figure E)

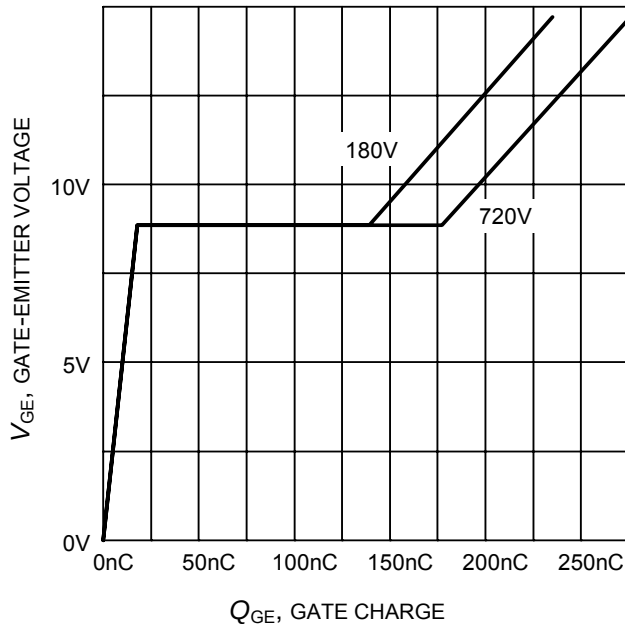


Figure 16. Typical gate charge
($I_C=30\text{ A}$)

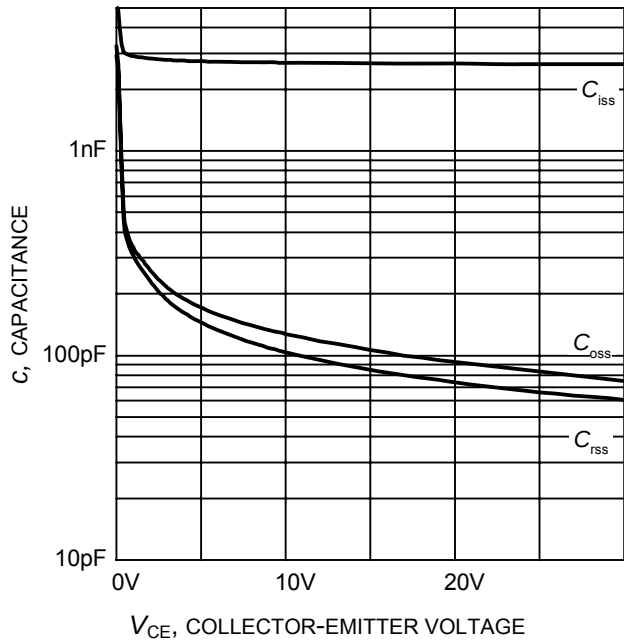


Figure 17. Typical capacitance as a function of collector-emitter voltage
($V_{GE}=0\text{V}$, $f=1\text{ MHz}$)

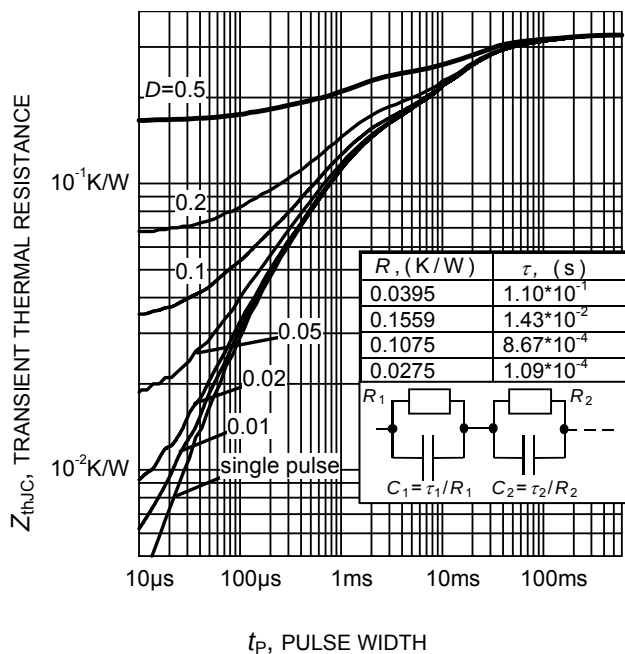


Figure 18. IGBT transient thermal resistance
($D = t_p / T$)

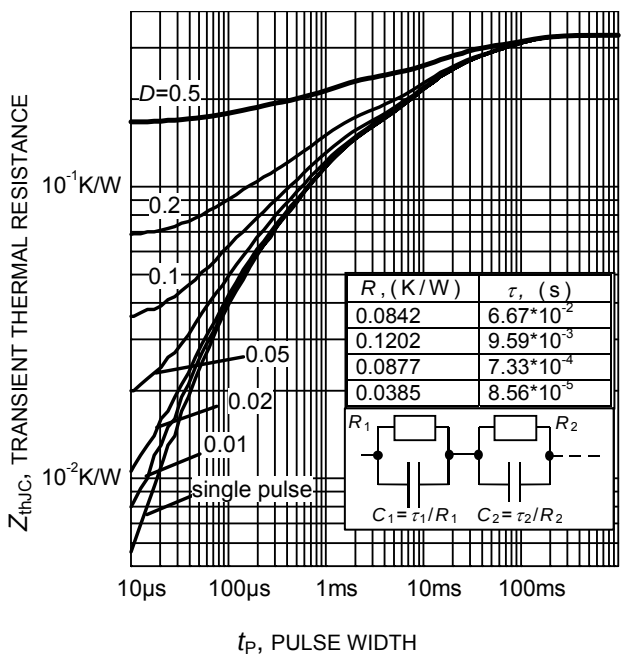


Figure 19. Typical Diode transient thermal impedance as a function of pulse width
($D=t_p/T$)

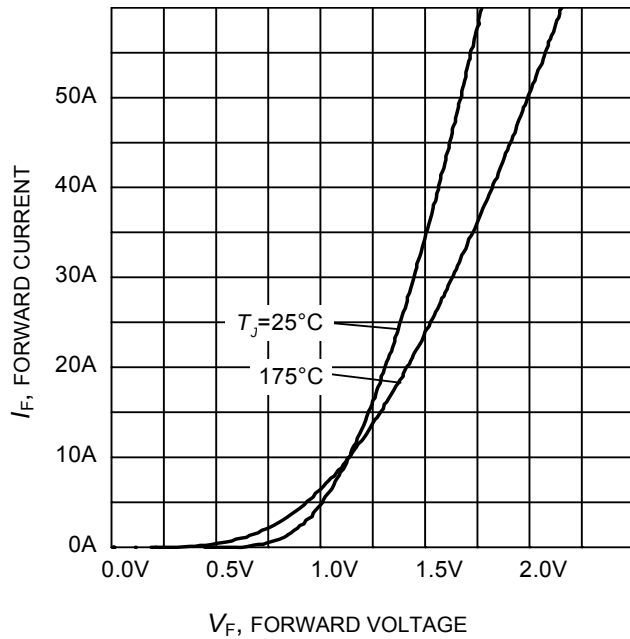


Figure 20. Typical diode forward current as a function of forward voltage

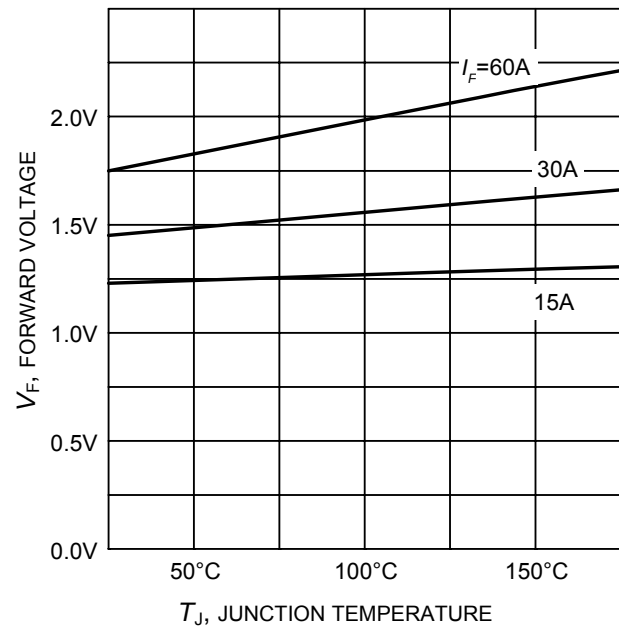
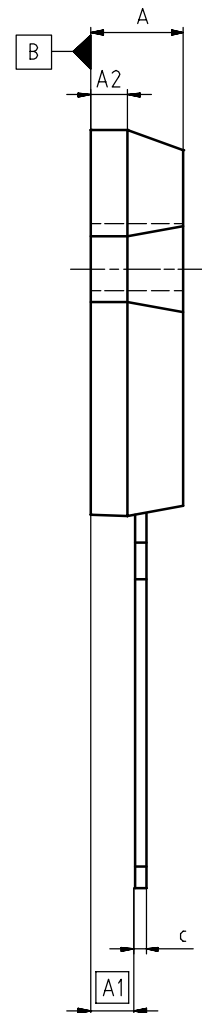
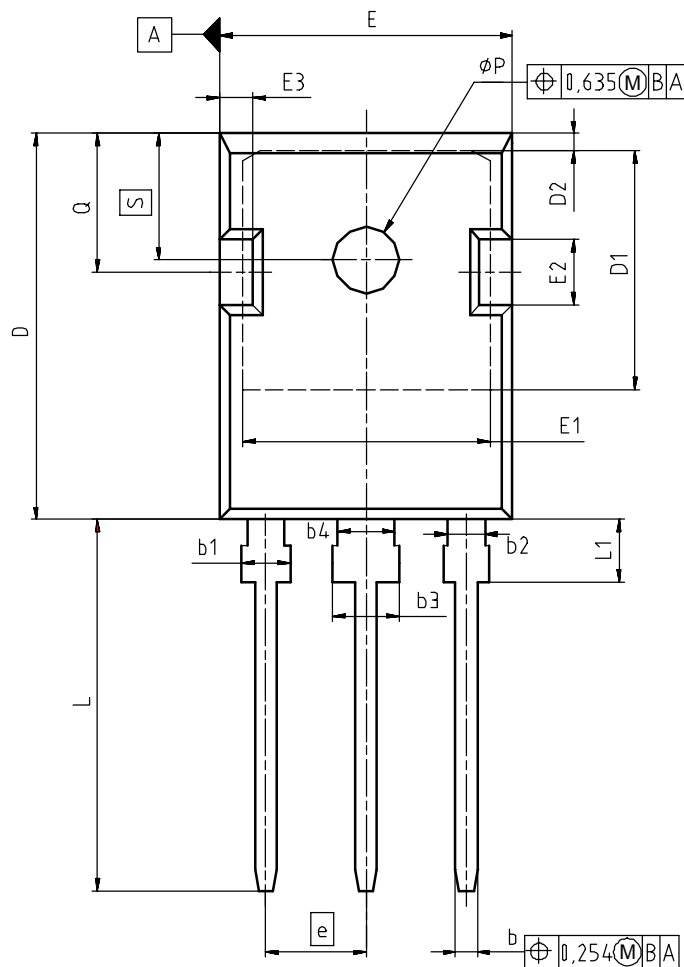
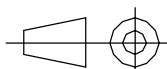


Figure 21. Typical diode forward voltage as a function of junction temperature

PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.82	21.10	0.820	0.831
D1	16.25	17.65	0.640	0.695
D2	1.05	1.35	0.041	0.053
E	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
φP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO. Z8B00003327
SCALE 0 5 5 7.5mm
EUROPEAN PROJECTION 
ISSUE DATE 17-12-2007
REVISION 03

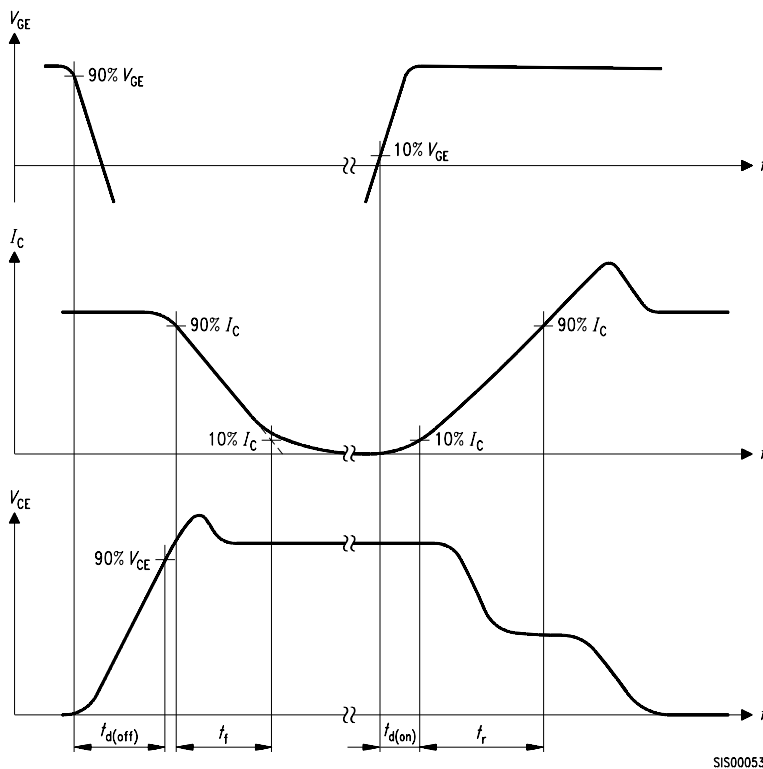


Figure A. Definition of switching times

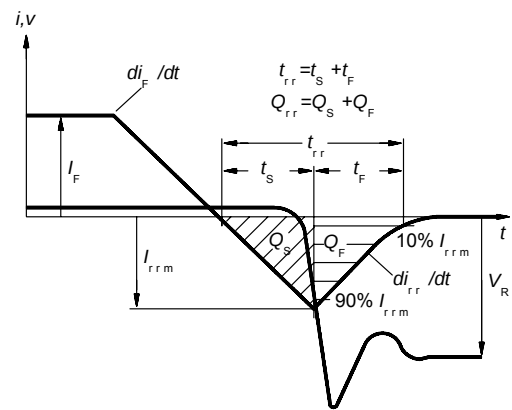


Figure C. Definition of diodes switching characteristics

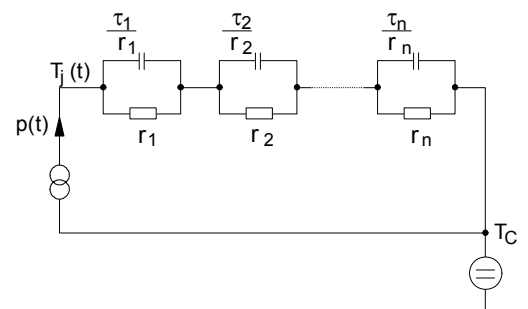


Figure D. Thermal equivalent circuit

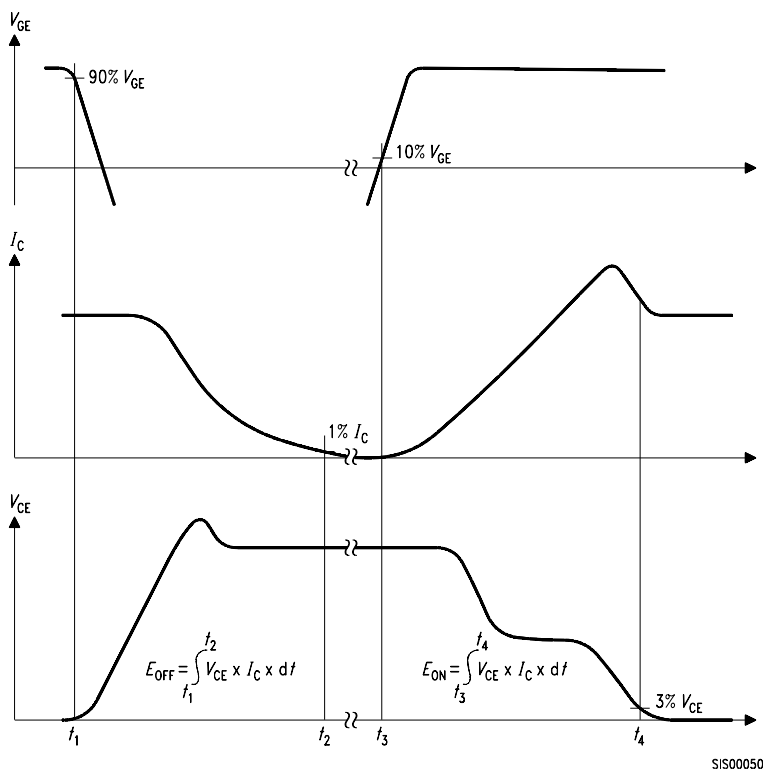


Figure B. Definition of switching losses

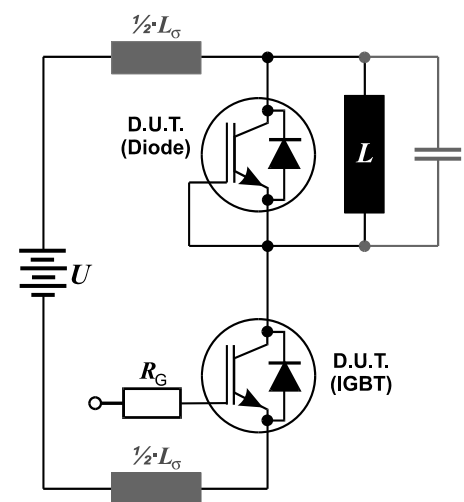


Figure E. Dynamic test circuit

Published by
Infineon Technologies AG
81726 Munich, Germany
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